



SL Grade

AsahiKASEI

Mechanical Purging Compound for Injection Molding & Extrusion

Packaging



SL Grade is available in :
20kg bags (pictured above)



PICTURED: Close-up of SL Grade

Product Safety

Refer to SDS
for more information

Key Measurements

Specific Gravity	1.00~1.11
Softening Point	80°C

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<https://www.asahi-kasei.co.jp/asaclean/en/>

Description & Benefits

- **Special grade for shutdown & sealing**
- **Low residue purge**
 - * Ideal for transparent or unreinforced application
 - * Excellent chaser to newEX grade to ensure maximum cleaning with minimum residue
- **Suitable for low-temperature resins**

Usage Information

Temperature Range :	150°C to 300°C
Applicant:	Injection Molding - including hot runners Extrusion - profile, sheet, blown film, compounding
Types of Resin:	Most commodity and engineering resins within the processing temperature range, particularly transparent, unreinforced or low-temperature resins.
Amount of Purge:	Typically 1-2 system capacities (actual amount depends on degree of contamination)
Minimum Clearance:	No minimum hot runner gate clearance requirement nor extrusion die or mesh clearance requirement.
Soaking Time:	Not required

* Detailed instruction may vary to optimize your purging process.

Physical & Chemical Properties

Pellet color:	Transparency and white are mixed
Base resin:	Styrenic resin
Inorganic additives:	Less than 10%
Stability:	Stable under normal temperatures
Reactivity:	Non-reactive under normal handling and storage conditions
Conditions to avoid:	Do not exceed recommended temperature range. Do not allow ASACLEAN SL Grade to reside in barrel for more than 30 minutes at temperatures higher than 280°C